**FOR IMMEDIATE RELEASE**

**[SAMTEC LOGO] July 2021**

**Samtec Releases Family of AcceleRate® HP** **High-Performance Arrays**

*Basis for new PICMG COM-HPC®Interconnect Solutions*

**New Albany, IN:** Samtec Inc., a privately held $800 MM global manufacturer of a broad line of electronic interconnect solutions, proudly announces the release of next-gen AcceleRate HP High-Performance Arrays. AcceleRate HP supports 112 Gbps PAM4 extreme performance in an ultra-micro footprint.

AcceleRate HP High-Performance Arrays feature an open-pin-field array which maximizes grounding and routing flexibility. System architects can route high-performance differential-pairs, single-ended signals and high-current voltage rails via the same interconnect.

Additionally, the 2.2 / 2.4 / 2.2 mm row pitch eases routing of differential signals. Crosstalk is improved with the increased space and the ability to add more ground vias around the differential signals.

“Samtec’s new AcceleRate HP High-Performance Arrays set the standard for high-speed 112 Gbps PAM4 performance in a small form factor,” said Michael Boone, Product Manager, High-Speed Board-to-Board at Samtec, Inc. “Fast-growing applications such as AI accelerators, ASIC emulators and next-gen edge computing platforms leverage these unique benefits.”

Key AcceleRate HP High-Performance Arrays features include:

* Dense 0.635 mm pitch
* Low-profile 5 mm and up to 10 mm stack heights
* Up to 400 total pins available
* Roadmap to 1,000+ pins
* Data rate compatible with PCIe® 5.0 and 100 GbE
* BGA termination for easy assembly and self-alignment

For more information on AcceleRate HP High-Performance Arrays, please visit [www.samtec.com/accelerateHP](http://www.samtec.com/accelerateHP).

**PICMG COM-HPC Connectors**

The new PICMG COM-HPC Specification provides system and interface flexibility by adopting a pair of 400 pin connectors based on Samtec's AcceleRate HP High-Performance Arrays. Samtec COM-HPC Connectors link carriers to Server and Client modules. They support existing and future interfaces such as PCIe5.0 and up to 100 GbE. The connector pairs support either a 5 mm or 10 mm stack height.

For more information on Samtec COM-HPC Connectors, please download the [COM-HPCInterconnect Solutions eBrochure](https://suddendocs.samtec.com/ebrochures/samtec-com-hpc-ebrochure.pdf), visit [www.samtec.com/COMHPC](http://www.samtec.com/COMHPC) or e-mail our technical experts at [COMHPC@samtec.com](mailto:COMHPC@samtec.com).

**About Samtec**Founded in 1976, Samtec is a privately held, $800 MM global manufacturer of a broad line of electronic interconnect solutions, including High-Speed Board-to-Board, High-Speed Cables, Mid-Board and Panel Optics, Precision RF, Flexible Stacking, and Micro/Rugged components and cables. With 40+ international locations and products sold in more than 125 different countries, Samtec’s global presence enables its unmatched customer service. For more information, please visit [http://www.samtec.com](http://www.samtec.com/).

**Samtec, Inc.**

**P.O. Box 1147**

**New Albany, IN 47151-1147**

**USA**

**Phone: 1-800-SAMTEC-9 (800-726-8329)**

[**www.samtec.com**](http://www.samtec.com)

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**PR Contact:**

Matt Burns

[matthew.burns@samtec.com](mailto:matthew.burns@samtec.com)

812-944-6733